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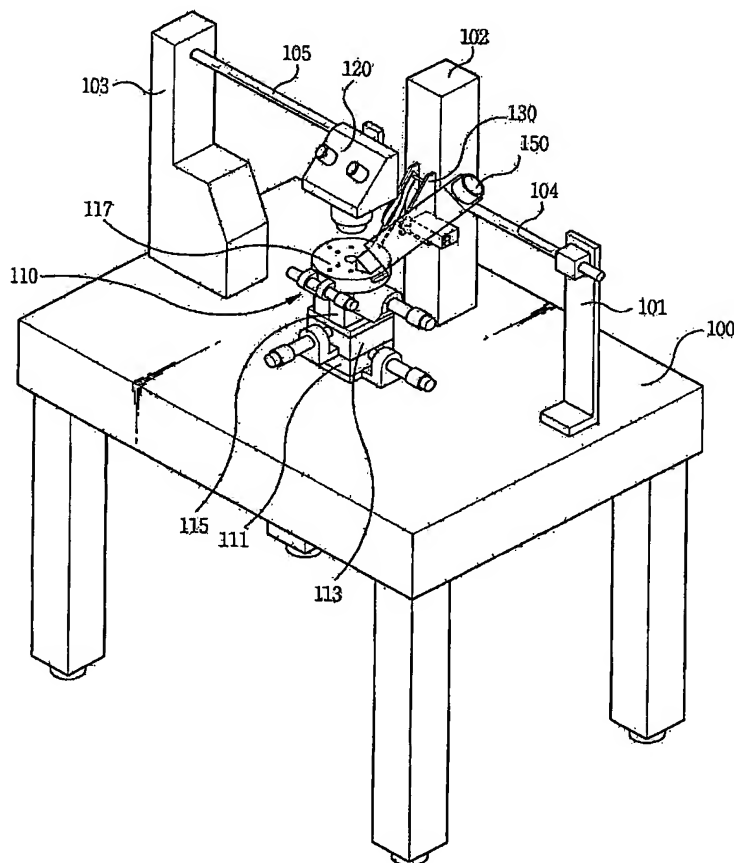
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- (71) Applicant (for all designated States except US): **PH-ICOM CORPORATION** [KR/KR]; 60-29 Gasan-dong, Kumchon-gu, Seoul 153-801 (KR).
- (72) Inventor; and
(75) Inventor/Applicant (for US only): **LEE, Jung-Hoon** [KR/KR]; 1315-1402 Dongpaik Woosung APT., 1059 Sanbon-2-dong, Kunpo-shi, Gyeonggi-do 435-849 (KR).
- (74) Agent: **KIM, Inhan**; 5th floor, Daerim Bldg., 1695-4 Seocho-dong, Seocho-gu, Seoul 137-883 (KR).
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(54) Title: PROBE POSITIONING AND BONDING DEVICE AND PROBE BONDING METHOD



(57) Abstract: Disclosed herein are a probe positioning and bonding device and a probe bonding method, and more particularly a probe positioning and bonding device used to fix probes to prescribed positions on a substrate so that a probe card used for semiconductor integrated circuit testing equipment is manufactured, and a probe bonding method using the same. The probe positioning and bonding device comprises a stage unit disposed on a working table, a microscope disposed above the stage unit while being supported by means of a first supporting member disposed on the working table, a probe fixing unit disposed above the stage unit and below the microscope while being supported by means of a second supporting member disposed on the working table, and a light source unit supported by means of a third supporting member disposed on the working table. The light source unit is disposed toward the upper part of the stage unit.



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